

1.0 SCOPE

This specification documents the detail requirements for space qualified product manufactured on Analog Devices, Inc.'s QML certified line per MIL-PRF-38535 Level V except as modified herein. The manufacturing flow described in the STANDARD SPACE LEVEL PRODUCTS PROGRAM brochure is to be considered a part of this specification. <http://www.analog.com/aerospace>. This data sheet specifically details the space grade version of this product. A more detailed operational description and a complete data sheet for commercial product grades can be found at www.analog.com/AD561.

2.0 Part Number. The complete part number(s) of this specification follow:

Part Number	Description
AD561-703D	Low Cost 10-Bit Monolithic D/A Converter

2.1 Case Outline.

Letter	Descriptive designator	Case Outline (Lead Finish per MIL-PRF-38535)
D	GDIP2-T16	16-Lead sidebraced dual-in-line package

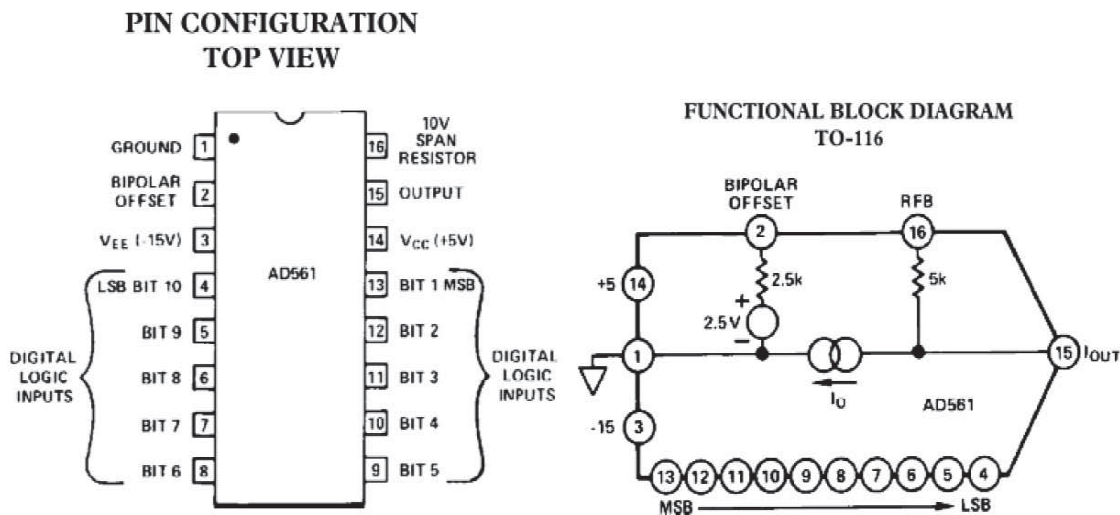


Figure 1 - Terminal connections.

ASD0011258

Rev. G

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AD561

3.0 Absolute Maximum Ratings. ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Operating Temperature Range	-55°C to +125°C
Storage Temperature Range	-65°C to +150°C
Power Dissipation	500mW
Lead Temperature (Soldering, 60 sec.)	300°C
Maximum Junction Temperature (T_J).....	+175°C
Supply Voltage	$\pm 16.5\text{V}$
Digital Input Voltage (V_{IN}).....	V_{CC} to Ground
Output Voltage Compliance (V_{OUT})	-2V to +10V
10V Span Resistor to Ground	V_{CC} to V_{EE}

3.1 Thermal Characteristics:

Thermal Resistance, Sidebrazed (D) Package
Junction-to-Case (Θ_{JC}) = 30°C/W Max
Junction-to-Ambient (Θ_{JA}) = 100°C/W Max

4.0 Electrical Table:

TABLE I

Parameter See notes at end of table	Symbol	Conditions (Note 1/)	Sub-group	Limit Min	Limit Max	Units
Relative Accuracy	RA	All Bits with + or - Errors on	1		1/2	LSB
Differential Nonlinearity	DNL	Major carry transitions	1, 2, 3		1	
Gain Error	A_E	With fixed 25Ω resistor	1		$\pm 1/2$	%FS
Gain Error TC	TCA_E		2, 3		± 60	ppm of FS /°C
Unipolar Offset Error	V_{OS}	Note 2	1		± 0.05	%FS
Unipolar Error TC	TCV_{OS}				± 10	ppm of FS /°C
Bipolar Zero Error	B_{PZE}	With 10Ω resistor	1		± 3.5	LSB
Bipolar Zero Error TC	TCB_{PZE}		2, 3		± 20	ppm of FS /°C
Output Current	I_{OUT}	Digital inputs at logic "1"	1	1.5	2.4	mA
Power Supply Gain Sensitivity	PSS1	V_{CC} , +4.5V to +5.5V V_{CC} , 13.5V to +16.5V	1		± 10	ppm of FS /%
	PSS2	V_{EE} , -10.8V to -13.2V V_{EE} , -13.2V to -16.5V	1		± 25	
Power Supply Current 2/	I_{CC}	V_{CC} , +4.5V to +16.5V	1		10	mA
	I_{EE}	V_{EE} , -10.8V to -16.5V	1		16	
Power Dissipation	PD		1		500	mW
Digital Input High Voltage	V_{IH}		1	2.0		V
Digital Input Low Voltage	V_{IL}		1		0.8	
Digital Input High Current	I_{IH}	Digital "1" = 15V	1		± 100	nA
Digital Input Low Current	I_{IL}	Digital "0" = 0V	1		± 25	μA

TABLE I NOTES:

- 1/ $V_{CC} = +5\text{V}$, $V_{EE} = -15\text{V}$, unless otherwise specified.
 2/ Also tested in CMOS mode. $V_{CC} = +15\text{V}$, $V_{EE} = -15\text{V}$, $V_{IH} = 10.5\text{V}$, $V_{IL} = 4.5\text{V}$.

4.1 Electrical Test Requirements:

Table II	
Test Requirements	Subgroups (in accordance with MIL-PRF-38535, Table III)
Interim Electrical Parameters	1
Final Electrical Parameters	1, 2, 3 <u>1/ 2/</u>
Group A Test Requirements	1, 2, 3
Group C end-point electrical parameters	1 <u>2/</u>
Group D end-point electrical parameters	1
Group E end-point electrical parameters	1

1/ PDA applies to Subgroup 1. Deltas excluded from PDA
2/ See table III for delta parameters and limits.

4.2 Table III. Lifetest / Burn-in delta limits.

Table III				
TEST TITLE	BURN-IN ENDPOINT	LIFETEST ENDPOINT	DELTA LIMIT	UNITS
I _{CC}	10	10	±3	mA
I _{EE}	16	16	±3	mA
B _{PZE}	±3.5	±3.5	±2	LSB

5.0 Life Test/Burn-In Circuit:

- 5.1 HTRB is not applicable for this drawing.
- 5.2 Burn-in is per MIL-STD-883 Method 1015 test condition B.
- 5.3 Steady state life test is per MIL-STD-883 Method 1005.

Rev	Description of Change	Date
A	Initiate	6/30/2000
B	Correct Typo's in Table I. No limits changed. Update Table III.	6/29/2001
C	Update web address. Delete subgroups 4, 5, & 6 from Table II as they are not on Table I.	2/20/2002
D	Update web address. Delete Burn-in Circuit.	6/20/2003
E	Correct Typo's in 2.1 Case Outline, Descriptive designator. Change from GDIP1-T16 to GDIP2-T16.	11/18/2003
F	Update header/footer & add to 1.0 Scope description.	2/21/2008
G	Remove obsolete part number and update ASD to ADI Standard	11/22/2011